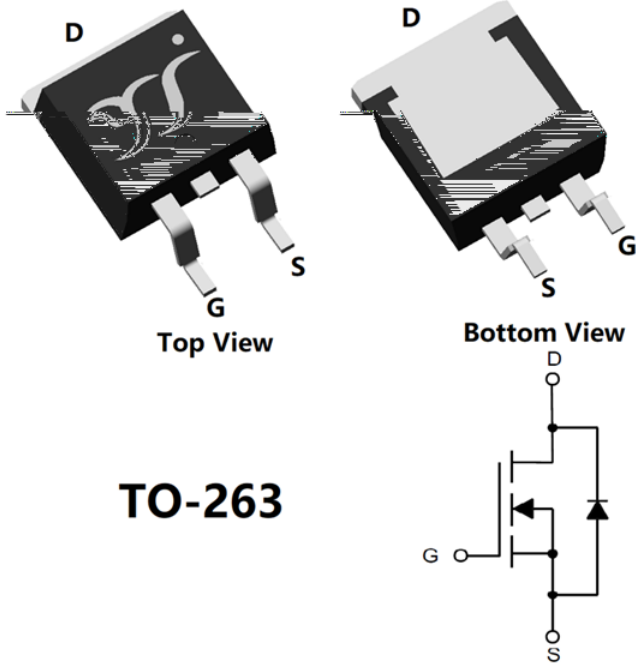


N-Channel Enhancement Mode Field Effect Transistor



TO-263

Product Summary

V_{DS}	60V
I_D	200A
$R_{DS(ON)}$ (at $V_{GS}=10V$)	<3.2 mohm
$R_{DS(ON)}$ (at $V_{GS}=4.5V$)	<4.5 mohm
100% EAS Tested	
100% ∇V_{DS} Tested	

General Description

- Excellent package for heat dissipation
- High density cell design for low $R_{DS(ON)}$
- Moisture Sensitivity Level 1
- Epoxy Meets UL 94 V-0 Flammability Rating
- Halogen Free
- Part no. with suffix "Q" means AEC-Q101 qualified

Applications

- Consumer electronic power supply
- Isolated DC-DC Converters
- Motor control
- Invertors

Absolute Maximum Ratings ($T_A=25^\circ\text{C}$ unless otherwise noted)

Parameter		Symbol	Limit	Unit
Drain-source Voltage		V_{DS}	60	V
Gate-source Voltage		V_{GS}	± 20	V
Drain Current ^A	$T_A=25^\circ\text{C}$	I_D	23	A
	$T_A=100^\circ\text{C}$		15	
	$T_C=25^\circ\text{C}$		200	
	$T_C=100^\circ\text{C}$		125	
Pulsed Drain Current ^B		I_{DM}	600	A
Avalanche energy ^C		EAS	600	mJ
Total Power Dissipation ^D	$T_A=25^\circ\text{C}$	P_D	4.3	W
	$T_A=100^\circ\text{C}$		1.7	
	$T_C=25^\circ\text{C}$		260	
	$T_C=100^\circ\text{C}$		104	
Junction and Storage Temperature Range		T_J, T_{STG}	-55~+150	$^\circ\text{C}$



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Thermal resistance

Parameter		Symbol	Typ	Max	Units
Thermal Resistance Junction-to-Ambient ^E	Steady-State	R _{JA}	24	29	/W
Thermal Resistance Junction-to-Case	Steady-State	R _{JC}	0.4	0.48	

Ordering Information (Example)

PREFERED P/N	PACKING CODE	Marking	MINIMUM PACKAGE(pcs)	INNER BOX QUANTITY(pcs)	OUTER CARTON QUANTITY(pcs)	DELIVERY MODE
YJB200G06CQ	F2	YJB200G06C	800	/	8000	13" reel



YJB200G06CQ

Electrical Characteristics (T_J=25 °C unless otherwise noted)

Parameter	Symbol	Conditions	Min	Typ	Max	Units
Static Parameter						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} = 0V, I _D =250μA	60			V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =60V, V _{GS} =0V			1	μA
Gate-Body Leakage Current	I _{GSS}	V _{GS} = ±20V, V _{DS} =0V			±100	nA
Gate Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D =250μA	1.0	1.6	2.5	V
Static Drain-Source On-Resistance	R _{DS(on)}	V _{GS} = 10V, I _D =20A		2.5	3.2	m
		V _{GS} = 4.5V, I _D =15A		3	4.5	
Diode Forward Voltage	V _{SD}	I _S =20A, V _{GS} =0V			1.2	V
Dynamic Parameters						
Gate resistance	R _G	f=1MHz		2		
Input Capacitance	C _{iss}	V _{DS} =25V, V _{GS} =0V, f=100KHZ		6000		pF
Output Capacitance	C _{oss}			1300		
Reverse Transfer Capacitance	C _{rss}			47		
Switching Parameters						
Total Gate Charge	Q _g	V _{GS} =10V, V _{DS} =30V, I _D =45A		85		nC
Gate-Source Charge	Q _{gs}			23		
Gate-Drain Charge	Q _{gd}			9.3		
Reverse Recovery Charge	Q _{rr}	I _S =45A, di/dt=100A/us,		61		
Reverse Recovery Time	t _{rr}			54		
Turn-on Delay Time	t _{d(on)}	V _{GS} =10V, V _{DS} =30V, I _D =45A R _{GEN} =3		18.5		ns
Turn-on Rise Time	t _r			87		
Turn-off Delay Time	t _{d(off)}			64		
Turn-off fall Time	t _f			107		

Note:

- The maximum current rating is package limited.
- Repetitive rating; pulse width limited by max. junction temperature.
- T_J=25 °C, V_{DD}=50V, V_{GS}=10V, R_G=25 Ω, L=0.5mH, I_{AS}=49A.
- P_D is based on max. junction temperature, using junction-case thermal resistance.
- The value of R_{JA} is measured with the device mounted on 1 in 2 FR-4 board with 2oz. Copper, in a still air environment with Ta=25 °C.



■ Typical Performance Characteristics

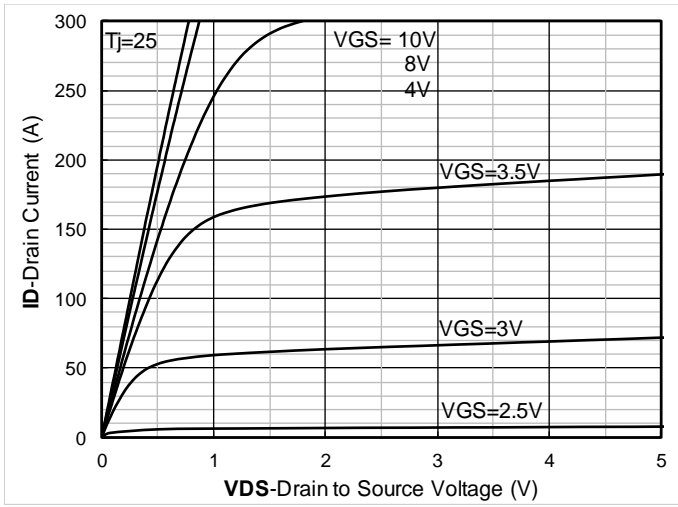


Figure1. Output Characteristics

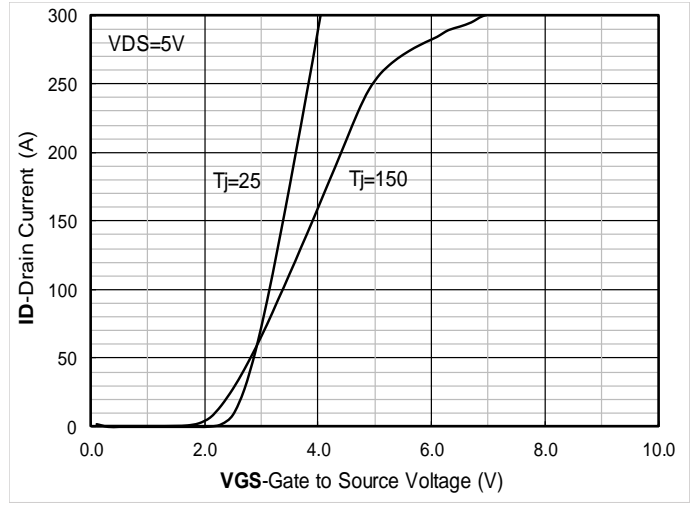


Figure2. Transfer Characteristics

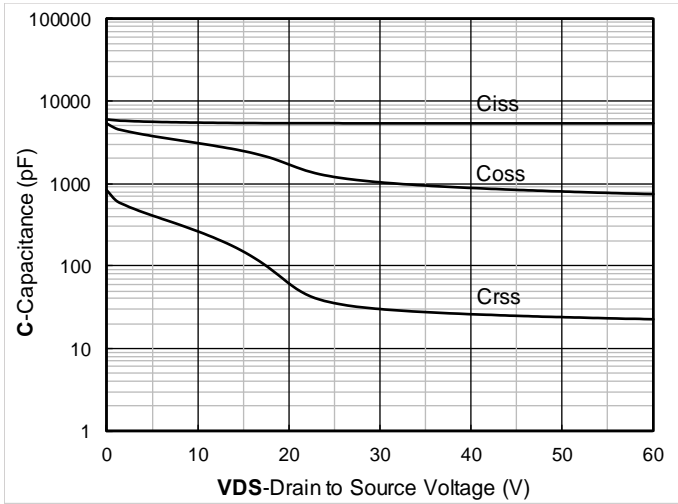


Figure3. Capacitance Characteristics

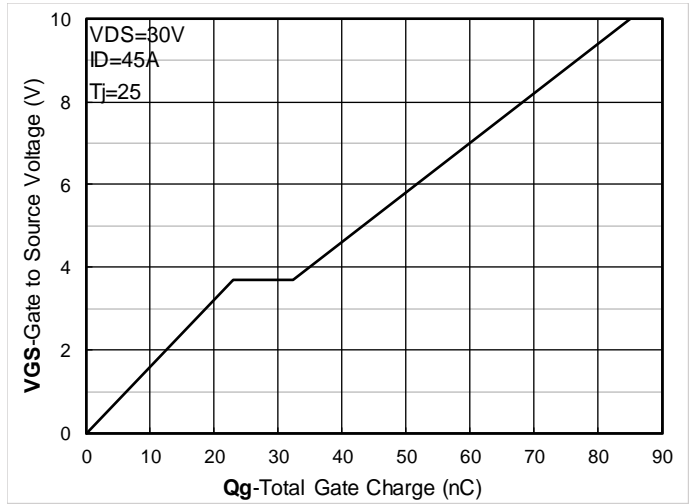


Figure4. Gate Charge

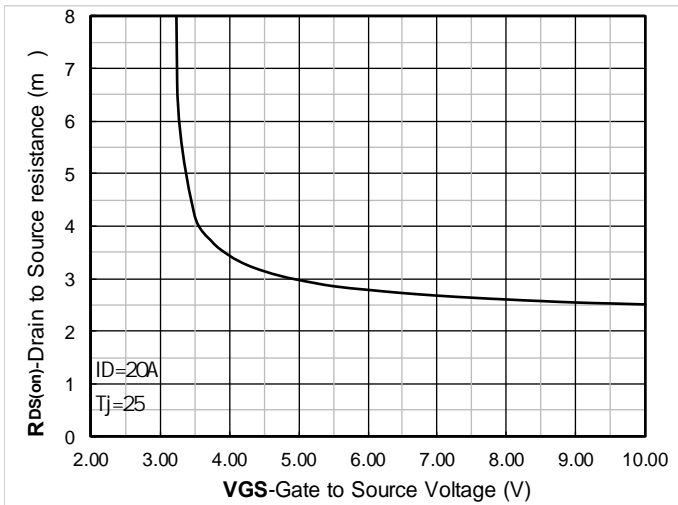


Figure 5. On-Resistance vs Gate to Source Voltage

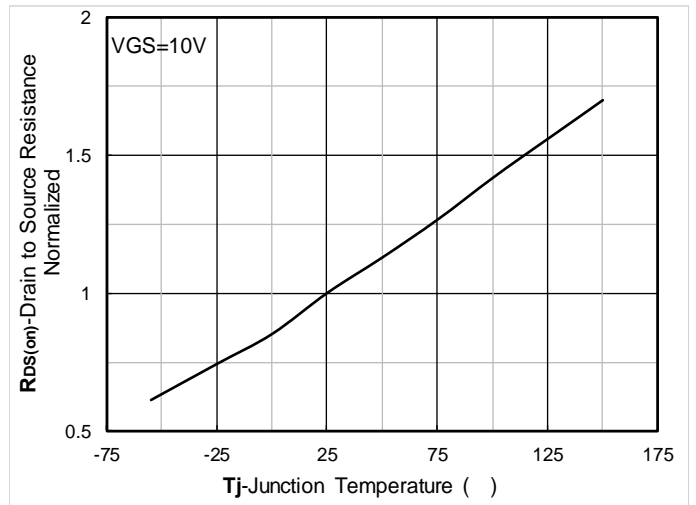


Figure 6. Normalized On-Resistance

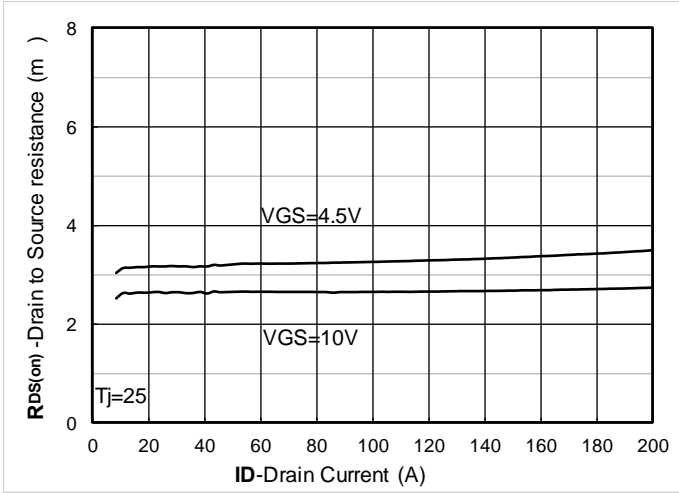


Figure 7. RDS(on) VS Drain Current

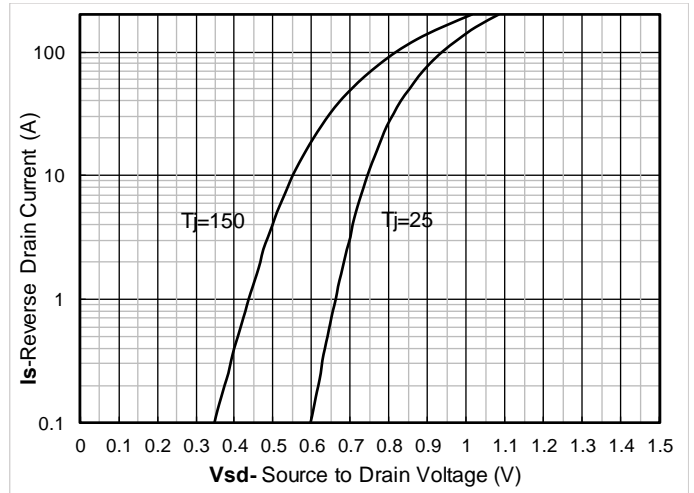


Figure 8. Forward characteristics of reverse diode

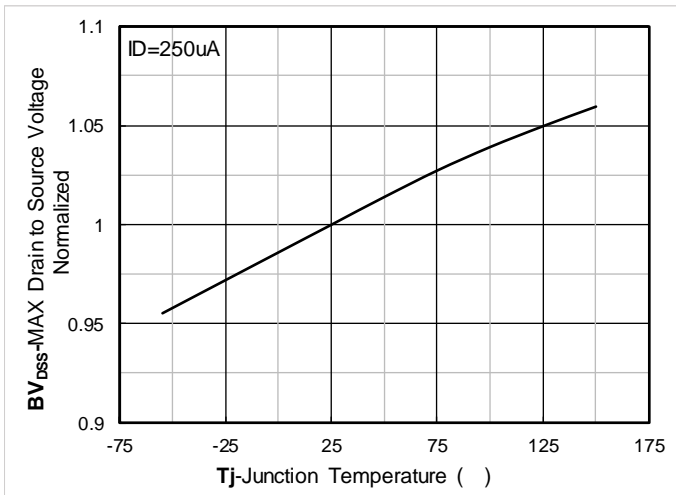


Figure 9. Normalized breakdown voltage

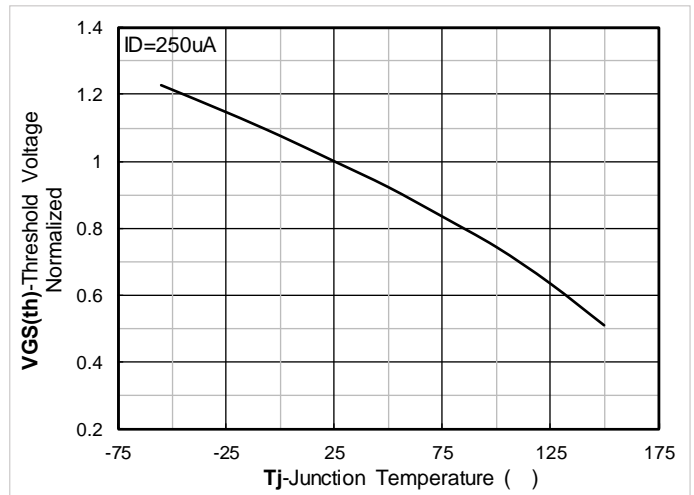


Figure 10. Normalized Threshold voltage

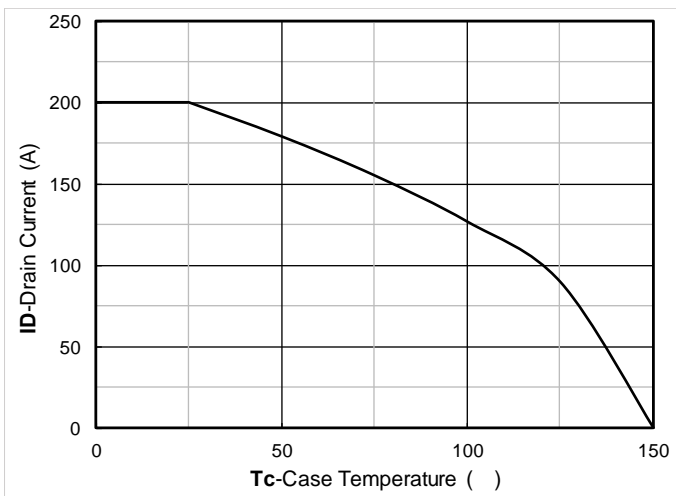


Figure 11. Current dissipation

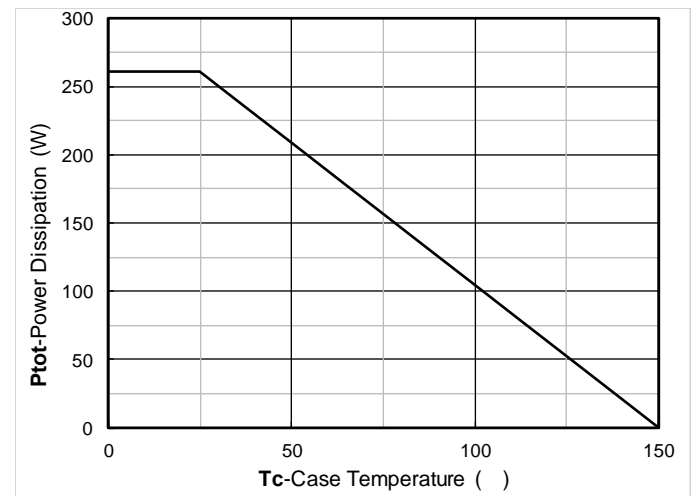


Figure 12. Power dissipation



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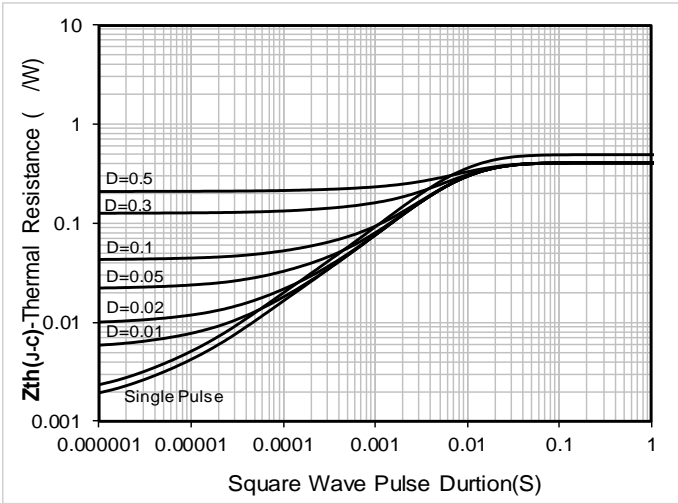


Figure 13. Maximum Transient Thermal Impedance

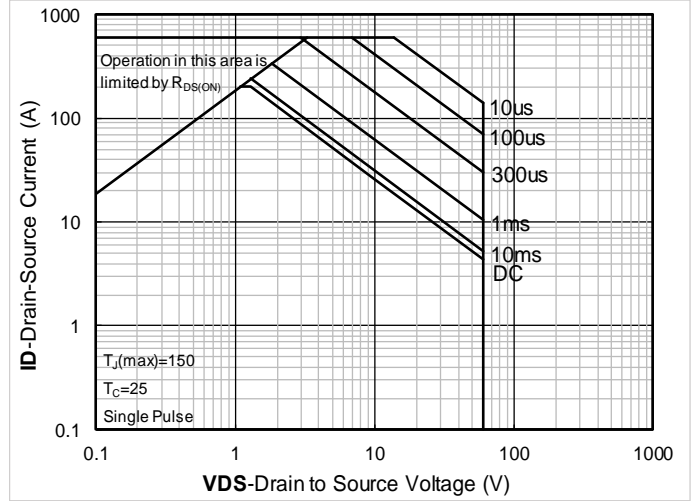
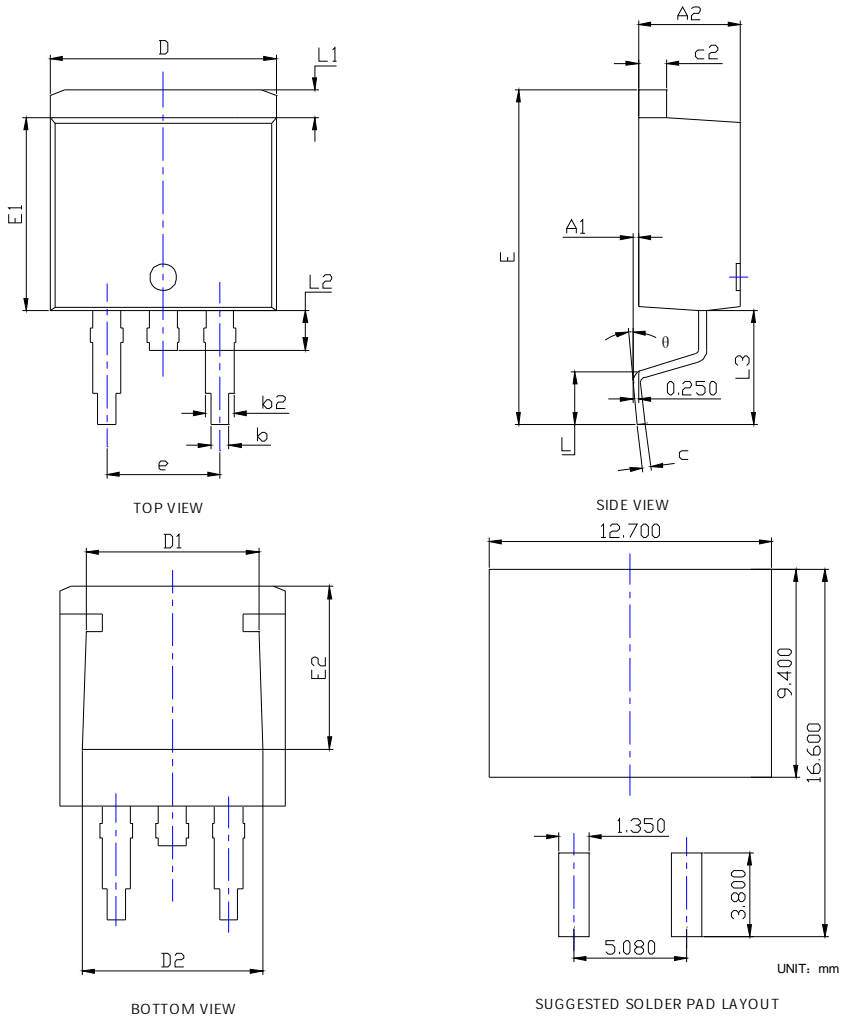


Figure 14. Safe Operation Area



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TO-263-HY Package information



SYMBOL	DIMENSIONS					
	INCHES			Millimeter		
	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.
A1	0.000	---	0.010	0.000	---	0.250
A2	0.174	0.180	0.186	4.430	4.580	4.730
b	0.028	0.032	0.036	0.720	0.820	0.920
b2	0.046	0.050	0.054	1.180	1.280	1.380
c	0.013	0.015	0.018	0.330	0.390	0.450
c2	0.048	0.050	0.053	1.220	1.280	1.340
D	0.394	0.400	0.406	10.000	10.150	10.300
D1	0.295	0.307	0.319	7.500	7.800	8.100
D2	0.303	0.315	0.327	7.700	8.000	8.300
E	0.571	0.591	0.610	14.500	15.000	15.500
E1	0.337	0.341	0.348	8.550	8.700	8.850
E2	0.276	0.287	0.299	7.000	7.300	7.600
e	0.200BSC			5.080BSC		
L	0.070	---	0.110	1.790	---	2.790
L1	0.044	---	0.056	1.120	---	1.420
L2	0.030	---	0.070	0.770	---	1.770
L3	0.197REF			5.000REF		
θ	0°	---	8°	0°	---	8°

NOTE:
 1. PACKAGE BODY SIZES EXCLUDE MOLD FLASH AND GATE BURRS.
 2. TOLERANCE 0.1mm UNLESS OTHERWISE SPECIFIED.
 3. THE PAD LAYOUT IS FOR REFERENCE PURPOSES ONLY.



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